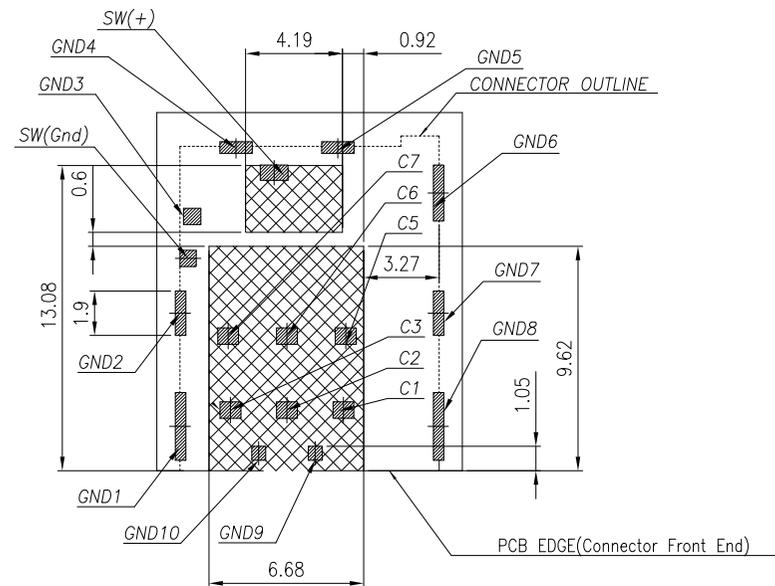
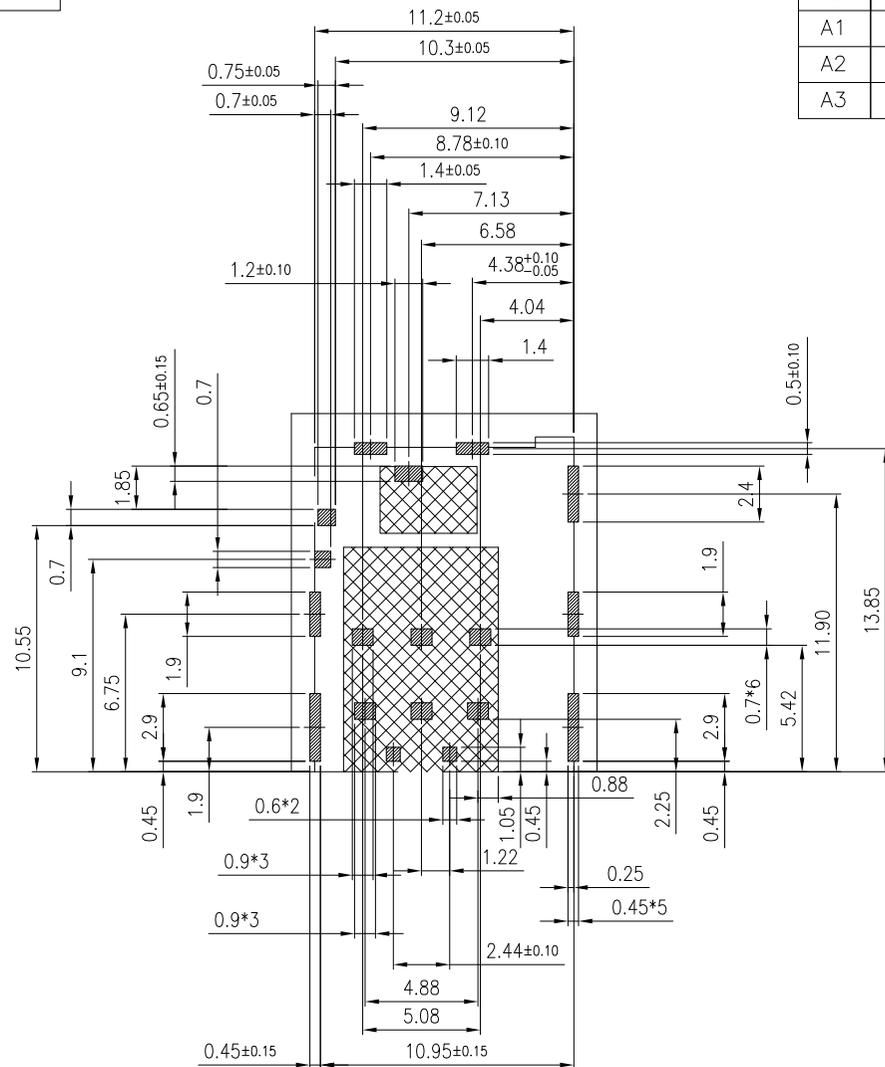




# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2018/06/20	Phebe Su
A1			Change shell type	2019/12/03	Phebe Su
A2			Change dimension	2020/07/25	Hanson
A3			Add dimension	2021/03/04	Hanson



NO PATTERN AND VIA HOLE IN HTIS AREA  
 SMT SOLDER AREA

RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)  
 RECOMMENDED METAL MASK T=0.12MM



Matrix Electronics Co.,Ltd

<b>TOLERANCE:</b> X:X ±0.25 X:XX ±0.20 X:XXX ±0.10 ANGLE: ±3°	DESIGN BY :	DATE :	PART NAME:	
	Hanson Huang	2021/03/04	Nano SIM card 1.25H	
UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY:	DATE :	PART NO.	MSM-01-01-06-12-60
	Janice Liu	2021/03/04		
	APPROVED BY1:	DATE :	MOLD NO.	NA
	Richard Hsieh	2021/03/04		
	APPROVED BY2:	DATE :	DRAW NO.	
	Richard Hsieh	2021/03/04	SHEET NO.	2 OF 2